Sensitive Gate Silicon Controlled Rectifiers Reverse Blocking Thyristors

Glassivated PNPN devices designed for high volume consumer applications such as temperature, light, and speed control; process and remote control, and warning systems where reliability of operation is important.

Features

- Glassivated Surface for Reliability and Uniformity
- Power Rated at Economical Prices
- Practical Level Triggering and Holding Characteristics
- Flat, Rugged, Thermopad Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Sensitive Gate Triggering
- These are Pb-Free Devices

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Мах	Unit
Peak Repetitive Off–State Voltage (Note 1) (Sine Wave, 50–60 Hz, $R_{GK} = 1 k\Omega$, $T_{C} = -40^{\circ}$ to 110°C)	V _{DRM,} V _{RRM}		V
C106B C106D, C106D1* C106M, C106M1*		200 400 600	
On-State RMS Current (180° Conduction Angles, T _C = 80°C)	I _{T(RMS)}	4.0	A
Average On-State Current (180° Conduction Angles, T _C = 80°C)	I _{T(AV)}	2.55	A
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = +25°C)	I _{TSM}	20	A
Circuit Fusing Considerations (t = 8.3 ms)	l ² t	1.65	A ² s
Forward Peak Gate Power (Pulse Width \leq 1.0 µsec, T _C = 80°C)	P _{GM}	0.5	W
Forward Average Gate Power (Pulse Width \leq 1.0 μ sec, T _C = 80°C)	P _{G(AV)}	0.1	W
Forward Peak Gate Current (Pulse Width \leq 1.0 μ sec, T _C = 80°C)	I _{GM}	0.2	A
Operating Junction Temperature Range	ТJ	−40 to +110	°C
Storage Temperature Range	T _{stg}	−40 to +150	°C
Mounting Torque (Note 2)	-	6.0	in. lb.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.
- Torque rating applies with use of compression washer (B52200F006). Mounting torque in excess of 6 in. lb. does not appreciably lower case-to-sink thermal resistance. Anode lead and heatsink contact pad are common.



ON Semiconductor®

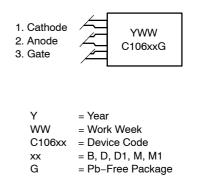
http://onsemi.com

SCRs 4 A RMS, 200 – 600 Volts





MARKING DIAGRAM & PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

THERMAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.0	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	75	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8 in. from Case for 10 Seconds	ΤL	260	°C

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted.)

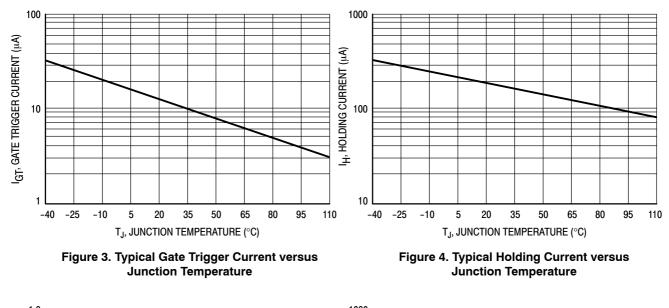
Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						-
Peak Repetitive Forward or Reverse Blocking Current (V _{AK} = Rated V _{DRM} or V _{RRM} , R _{GK} = 1 k Ω)	T _J = 25°C T _J = 110°C	I _{DRM} , I _{RRM}			10 100	μ Α μΑ
ON CHARACTERISTICS						
Peak Forward On-State Voltage (Note 3) (I _{TM} = 4 A)		V _{TM}	_	_	2.2	V
Gate Trigger Current (Continuous dc) (Note 4) $(V_{AK} = 6 \text{ Vdc}, R_L = 100 \Omega)$	$T_J = 25^{\circ}C$ $T_J = -40^{\circ}C$	I _{GT}		15 35	200 500	μΑ
Peak Reverse Gate Voltage (I _{GR} = 10 μA)		V _{GRM}	-	-	6.0	V
Gate Trigger Voltage (Continuous dc) (Note 4) $(V_{AK} = 6 \text{ Vdc}, R_L = 100 \Omega)$	$T_J = 25^{\circ}C$ $T_J = -40^{\circ}C$	V _{GT}	0.4 0.5	0.60 0.75	0.8 1.0	V
Gate Non-Trigger Voltage (Continuous dc) (Note 4) $(V_{AK} = 12 \text{ V}, \text{ R}_L = 100 \Omega, \text{ T}_J = 110^{\circ}\text{C})$		V _{GD}	0.2	_	_	V
Latching Current (V _{AK} = 12 V, I _G = 20 mA, R _{GK} = 1 k Ω)	$T_J = 25^{\circ}C$ $T_J = -40^{\circ}C$	ΙL		0.20 0.35	5.0 7.0	mA
Holding Current (V _D = 12 Vdc) (Initiating Current = 20 mA, R_{GK} = 1 k Ω)	$T_J = 25^{\circ}C$ $T_J = -40^{\circ}C$ $T_J = +110^{\circ}C$	l _Η		0.19 0.33 0.07	3.0 6.0 2.0	mA

Critical Rate-of-Rise of Off-State Voltage	dv/dt	-	8.0	-	V/μs
(V _{AK} = Rated V _{DRM} , Exponential Waveform, R_{GK} = 1 k Ω ,					
T _J = 110°C)					

Voltage Current Characteristic of SCR

+ Current

		+ Cu	Irrent Anode +
Symbol	Parameter		-V _{TM}
V _{DRM}	Peak Repetitive Off State Forward Voltage		
I _{DRM}	Peak Forward Blocking Current	on state /	
V _{RRM}	Peak Repetitive Off State Reverse Voltage	I _{RRM} at V _{RRM}	1
I _{RRM}	Peak Reverse Blocking Current		
V _{TM}	Peak On State Voltage		+ Voltage
I _H	Holding Current	Reverse Blocking Region	I _{DRM} at V _{DRM}
		(off state)	Forward Blocking Region
		\ Reverse Avalanche Region	(off state)
		Anode –	•
110			
100		12)	JUNCTION TEMPERATURE ≈ 110°C
		MAT	
ଦ୍ରି 90	DC	HALF SINE WAVE	
(2) 90 80 70 70 60 40 40 82 82 82 80 80 80 80 80 80 80 80 80 80 80 80 80			JCTIVE LOAD
70		🔂 6 −50 TO 400Hz.	
표 60			
≝ 50			DC
		Od l	
RESIS ⁴⁰ ⊂RESIS ث 30 – 50 to 4	TIVE OR INDUCTIVE LOAD.	ATE	
20			
			2 1.6 2.0 2.4 2.6 3.2 3.6 4.0
0.4			
	$I_{T(AV)}$ AVERAGE ON-STATE CURRENT (AMPERES)	≺ I _{T(AV)} AVERA Ŝ	GE ON-STATE CURRENT (AMPERES)
	Figure 1. Average Current Derating	🛎 Figure 2. Maxir	num On–State Power Dissipation



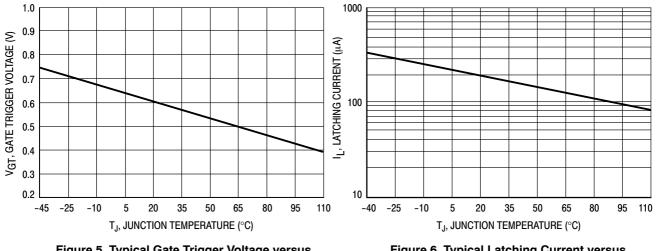
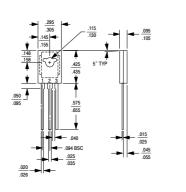


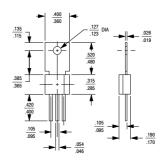
Figure 5. Typical Gate Trigger Voltage versus Junction Temperature

Figure 6. Typical Latching Current versus Junction Temperature

PACKAGE INTERCHANGEABILITY

The dimensional diagrams below compare the critical dimensions of the ON Semiconductor C-106 package with competitive devices. It has been demonstrated that the smaller dimensions of the ON Semiconductor package make it compatible in most lead-mount and chassis-mount applications. The user is advised to compare all critical dimensions for mounting compatibility.





ON Semiconductor C-106 Package

Competitive C-106 Package

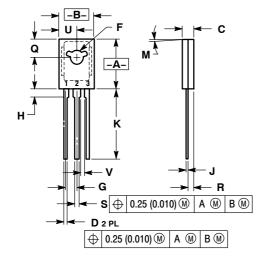
ORDERING INFORMATION

Device	Package	Shipping [†]
C106BG	TO-225AA (Pb-Free)	500 Units / Box
C106DG	TO-225AA (Pb-Free)	500 Units / Box
C106D1G*	TO-225AA (Pb-Free)	500 Units / Box
C106MG	TO-225AA (Pb-Free)	500 Units / Box
C106M1G*	TO-225AA (Pb-Free)	500 Units / Box

*D1 signifies European equivalent for D suffix and M1 signifies European equivalent for M suffix.

PACKAGE DIMENSIONS

TO-225 CASE 77-09 ISSUE Z



	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.425	0.435	10.80	11.04
В	0.295	0.305	7.50	7.74
C	0.095	0.105	2.42	2.66
D	0.020	0.026	0.51	0.66
F	0.115	0.130	2.93	3.30
G	0.094 BSC		2.39 BSC	
Н	0.050	0.095	1.27	2.41
J	0.015	0.025	0.39	0.63
K	0.575	0.655	14.61	16.63
М	5° TYP		5°	ТҮР
Q	0.148	0.158	3.76	4.01
R	0.045	0.065	1.15	1.65
S	0.025	0.035	0.64	0.88
U	0.145	0.155	3.69	3.93
٧	0.040		1.02	

1. DIMENSIONING AND TOLERANCING PER ANSI

CONTROLLING DIMENSION: INCH.

STYLE 2: PIN 1. CATHODE 2. ANODE 3. GATE

NOTES:

2.

Y14 5M 1982

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